

Amendments to the Claims

This listing of claims will replace all prior listings of claims in the application.

Listing of Claims

1. (Original) An electroless copper plating solution, wherein, along with a first reducing agent, hypophosphorous acid or a hypophosphite is used as a second reducing agent, and a stabilizer to inhibit copper deposition is further used at the same time.

2. (Original) An electroless copper plating solution according to Claim 1, which is used to produce a thin film with a thickness of 500 nm or less.

3. (Currently Amended) An electroless copper plating method, wherein an electroless copper plating solution according to Claim 1-~~or 2~~ is used to perform electroless copper plating on a mirror surface whose average surface roughness is less than 10 nm.